MSKSEMI 美森科
SEMICONDUCTOR

ESD TVS TSS MOV GDT PLED

MS50N06

Product specification

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

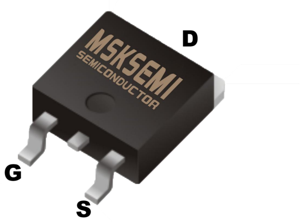
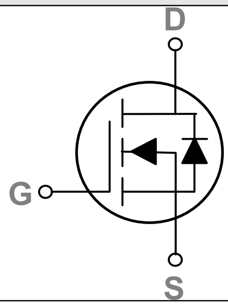
- 60V,50A,RDS(ON)=13mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

BVDSS	RDSON	ID
60V	13mΩ	50A

Applications

- Motor Drive
- Power Tools
- LED Lighting

Reference News

PACKAGE OUTLINE	N-Channel MOSFET	Marking
 TO-252		MSKSEMI 50N06 MS**

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (T_C=25°C)	50	A
	Drain Current – Continuous (T_C=100°C)	35	A
I_{DM}	Drain Current – Pulsed[1]	200	A
P_D	Power Dissipation (T_C=25°C)	65	W
	Power Dissipation – Derate above 25°C	0.5	W/°C
T_{STG}	Storage Temperature Range	-50 to 150	°C
T_J	Operating Junction Temperature Range	150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2	°C/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	60	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.07	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=60V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=48V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=20A	---	13	17	mΩ
		V_{GS}=4.5V , I_D=12A	---	15	25	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	1.6	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	5	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=10A	---	9	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[2,3]	V_{DS}=30V , V_{GS}=10V , I_D=15A	---	28	---	nC
Q_{gs}	Gate-Source Charge[2,3]		---	3.5	---	
Q_{gd}	Gate-Drain Charge[2,3]		---	6.5	---	
$T_{d(on)}$	Turn-On Delay Time[2,3]	V_{DD}=30V , V_{GS}=10V , R_G=6Ω I_D=1A	---	7.2	---	ns
T_r	Rise Time[2,3]		---	38	---	
$T_{d(off)}$	Turn-Off Delay Time[2,3]		---	34	---	
T_f	Fall Time[2,3]		---	8.2	---	
C_{iss}	Input Capacitance	V_{DS}=20V , V_{GS}=0V , F=1MHz	---	1680	---	pF
C_{oss}	Output Capacitance		---	115	---	
C_{rss}	Reverse Transfer Capacitance		---	85	---	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	2.2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	50	A
I_{SM}	Pulsed Source Current		---	---	100	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25°C , I_D=1mA	---	0.023	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=10A	---	18	25	mΩ
		V_{GS}=4.5V , I_D=8A		25	38	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	1.2	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.2	---	mV/°C
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J=25°C	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55°C	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=10A	---	5.5	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2.3	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=15V , V_{GS}=4.5V , I_D=10A	---	4.9	---	nC
Q_{gs}	Gate-Source Charge		---	1.66	---	
Q_{gd}	Gate-Drain Charge		---	1.85	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V , R_G=3.3 I_D=10A	---	1.6	---	ns
T_r	Rise Time		---	15.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	13	---	
T_f	Fall Time		---	4.8	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	416	---	pF
C_{oss}	Output Capacitance		---	62	---	
C_{rss}	Reverse Transfer Capacitance		---	51	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	24	A
I_{SM}	Pulsed Source Current[2,5]		---	---	50	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25°C	---	---	1.2	V
t_{rr}	Reverse Recovery Time	I_F=10A , dI/dt=100A/μs , T_J=25°C	---	8.7	---	nS
Q_{rr}	Reverse Recovery Charge		---	1.95	---	nC

Note :
1.Thce data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width .The EAS data shows Max. rating .
3.he test ondition is V≤ 300us , duty cycle $_{DD=25}$≤V,V 2%$_{GS}$ =10V,L=0.1mH,I_{AS}=12.7A
4.The power dissipation is limited by 150°C junction temperature
5.The data is theoretically the same asI_D and I_{DM} , in real applications , should be limited by total power dissipation.

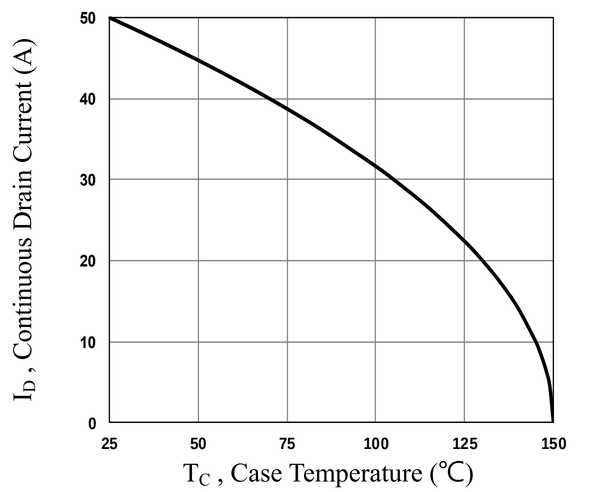


Fig.1 Continuous Drain Current vs. T_C

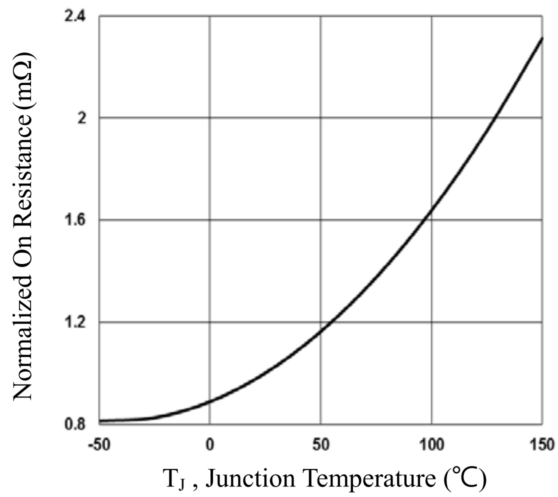


Fig.2 Normalized RDSON vs. T_J

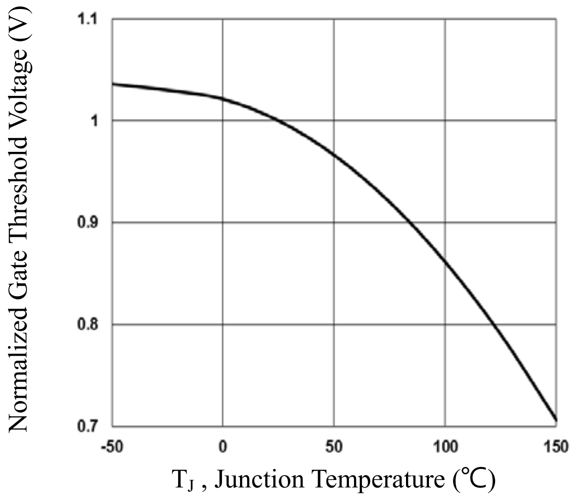


Fig.3 Normalized V_{th} vs. T_J

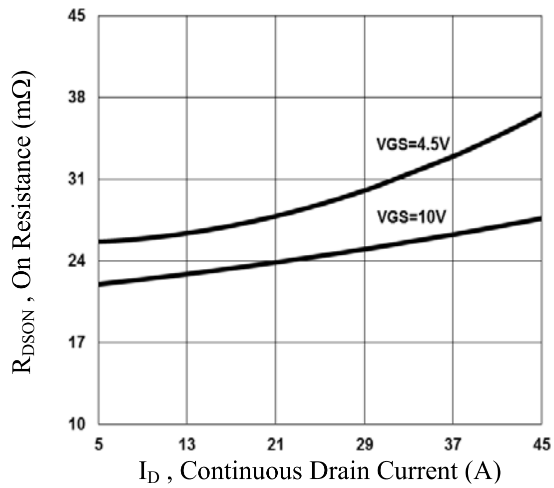


Fig.4 RDSON vs. Continuous Drain Current

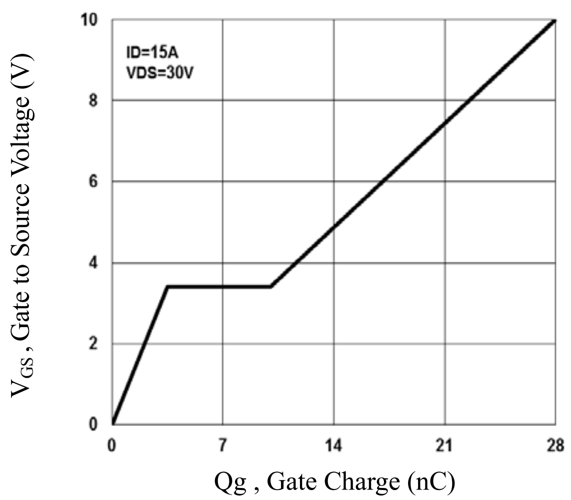


Fig.5 Gate Charge Waveform

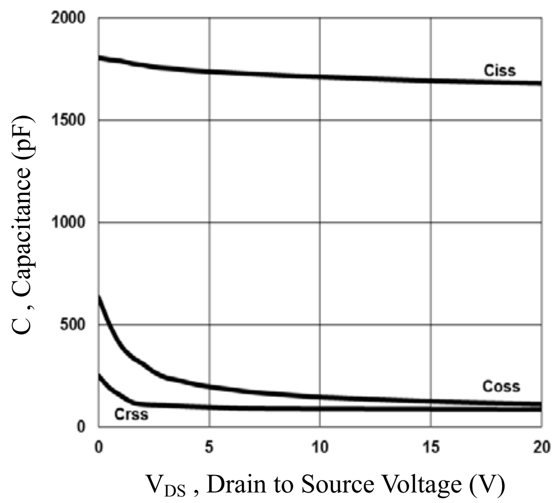


Fig.6 Capacitance Characteristics

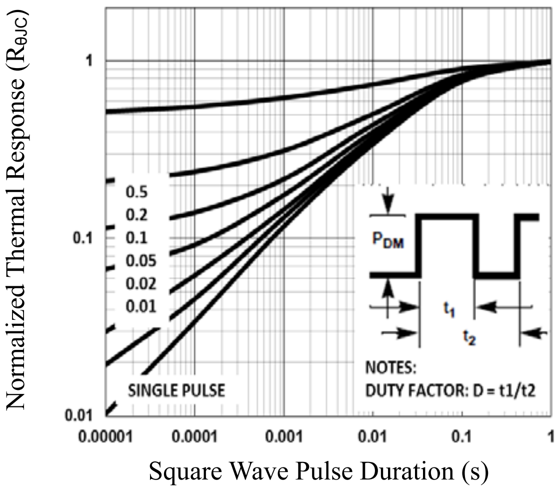


Fig.7 Normalized Transient Impedance

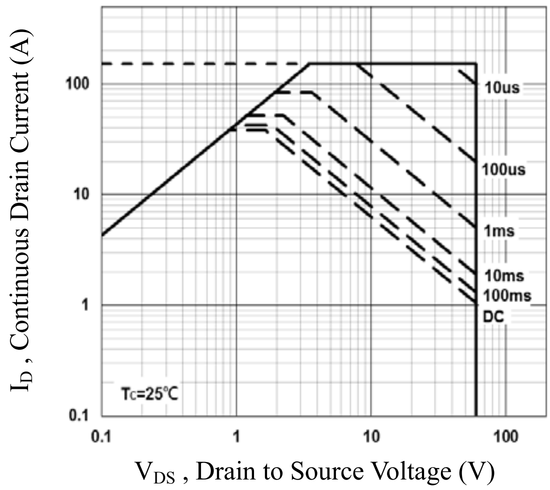
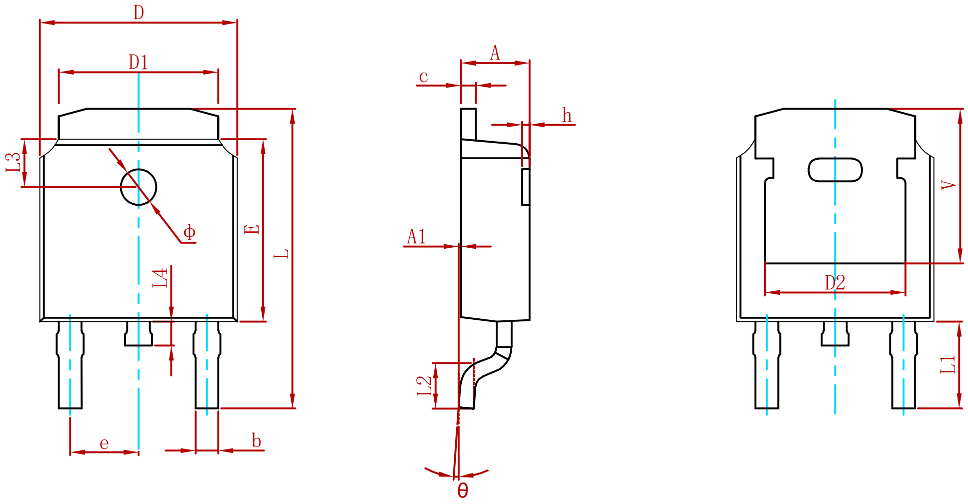


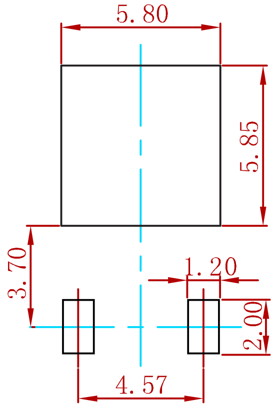
Fig.8 Maximum Safe Operation Area

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REELSPECIFICATION

P/N	PKG	QTY
MS50N06	TO-252	2500

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